

8/10/04

REMARKS

The present Amendment is in response to the Office Action having a mailing date of May 14, 2004. Claims 10-21 are pending in the present Application. Claims 10-21 are rejected. Claims 10 and 16 have been amended to overcome Examiner's objections. Claims 11-12 and 17-19 have been cancelled. Consequently, claims 10, 13-16 and 20-21 remain pending in the present application.

Claim Rejections-35 USC 112

The Examiner states,

2. Claims 10-16 are rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

It appears that the original specification does not have support for:

"the at least one metal being of sufficient thickness to carry a high current," which were not described/supported in the specifications.

Applicant has amended claims 10 and 16 to overcome this rejection.

Claim Rejections-35 USC 103

The Examiner states,

3. Claims 10-21 are rejected under U.S.C. 103(a) as being unpatentable over Yamada (6,008,127) in view of Dausch et al (6,359,374 B1).

Regarding claim 10, 16, Yamada, figures 1-38 (figures 33, 35, 36, 37, col. 8, lines 52-67, col. 9, lines 1-67), disclose a semiconductor device comprising: a semiconductor substrate 201 including a plurality of device structures (see figure 36) thereon; and an interconnect 235 on the semiconductor substrate, the interconnect comprising at least one slot 235 (see figure 33) provided in the semiconductor substrate and at least one metal 235 (aluminum) within the slot, wherein the at least one slot is oxidized everywhere (see col. 8, lines 52-67) except at the bottom of the slot where the interconnect forms a ground 225 (see col. 9, lines 58-65). Yamada fails to teach the at least one metal being of sufficient thickness to carry a high current.